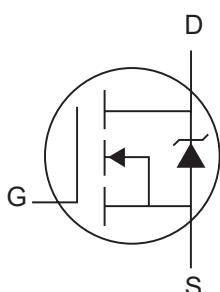
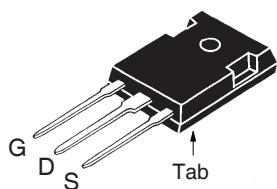


N-Channel Enhancement Mode MOSFET

MPR3N150PT

TO-247



V_{DS}	1500	V
$R_{DS(on),TYP}$	6.1	Ω
I_D	3	A

Features

- 1.Low on – resistance
- 2.Package TO-247

Applications

- 1.High Voltage Power Supplies
- 2.Capacitor Discharge Applications
- 3.Pulse Circuits

Maximum ratings, at $T_A = 25^\circ\text{C}$, unless otherwise specified

Absolute Maximum Ratings

PARAMETERS/TEST CONDITIONS	SYMBOL	LIMITS	UNITS
Drain-Source Voltage	V_{DS}	1500	V
Drain Current –continuous @ 25°C	I_D	3	A
Pulsed Drain Current ¹	I_{DM}	9	A
Gate-Source Voltage	V_{GS}	± 30	V
Single Pulse Avalanche	E_{AS}	250	mJ
Operating Junction & Storage Temperature	T_j, T_{stg}	-55 to 175	$^\circ\text{C}$
Maximum Power Dissipation $T_C=25^\circ\text{C}$	P_D	250	W
Thermal Resistance-Junction to Case	$R_{\theta JC}$	2	$^\circ\text{C}/\text{W}$
Thermal Resistance-Junction to Ambient	$R_{\theta JA}$	50	$^\circ\text{C}/\text{W}$

Note:

1. Pulse width limited by maximum junction temperature.

Electrical Characteristics

Symbol	Parameter	Condition	Min.	Typ.	Max.	Unit
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Static Electrical Characteristics @ $T_j=25^\circ\text{C}$ (unless otherwise stated)

V(BR)DSS	Drain-Source Breakdown Voltage	$V_{GS}=0\text{V}, I_D=250\mu\text{A}$	1510	1600	--	V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS}=1500\text{V}, V_{GS}=0\text{V}$	--	--	10	μA
I_{GSS}	Gate-Body Leakage Current	$V_{DS}=0\text{V}, V_{GS}=\pm 30\text{V}$	--	--	± 100	nA
$V_{GS(\text{th})}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=250\mu\text{A}$	3	3.85	5	V
$R_{DS(\text{on})}$	Drain-Source On-State Resistance	$V_{GS}=10\text{V}, I_D=1\text{A}$	--	6.1	7	Ω
V_{SD}	Forward on voltage (Note1)	$I_S=1\text{A}, V_{GS}=0\text{V}$	--	--	1.4	V

Dynamic Electrical Characteristics @ $T_j = 25^\circ\text{C}$ (unless otherwise stated)

C_{iss}	Input Capacitance	$V_{GS} = 0\text{V}, V_{DS} = 25\text{V}, f = 1\text{MHz}$	--	1375	--	pF
C_{oss}	Output Capacitance		--	90	--	pF
C_{rss}	Reverse Transfer Capacitance		--	30	--	pF
Q_g	Total Gate Charge	$V_{GS} = 10\text{V}, V_{DS} = 750\text{V}, I_D = 1.5$	--	38.6	--	nC
Q_{gs}	Gate-Source Charge		--	6.5	--	nC
Q_{gd}	Gate-Drain Charge		--	19	--	nC

Switching Characteristics

Td(on)	Turn-on Delay Time	V _{GS} = 10V, V _{DS} = 750V, I _D = 1.5A , R _G = 5Ω	--	19	--	ns
Tr	Turn-on Rise Time		--	21	--	ns
Td(off)	Turn-Off Delay Time		--	42	--	ns
Tf	Turn-Off Fall Time		--	25	--	ns

Source- Drain Diode Characteristics@ T_j = 25°C (unless otherwise stated)

I _S	Continuous Current	V _{GS} = 0V, T _j =25°C	--	--	3	A
T _{rr}	Reverse Recovery Time	IF = 1.5A, -di/dt = 100A/μs, V _R = 100V	--	--	0.9	us
Q _{rr}	Reverse Recovery Charge		--	--	6.7	uC

Typical Characteristics

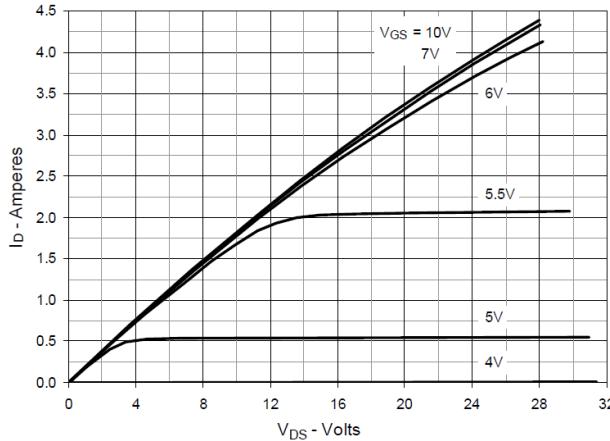
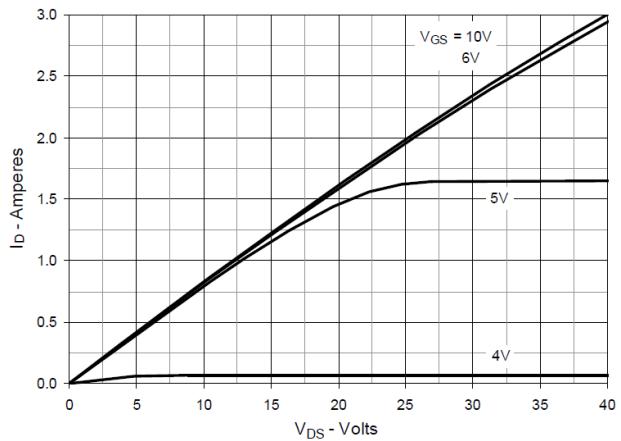
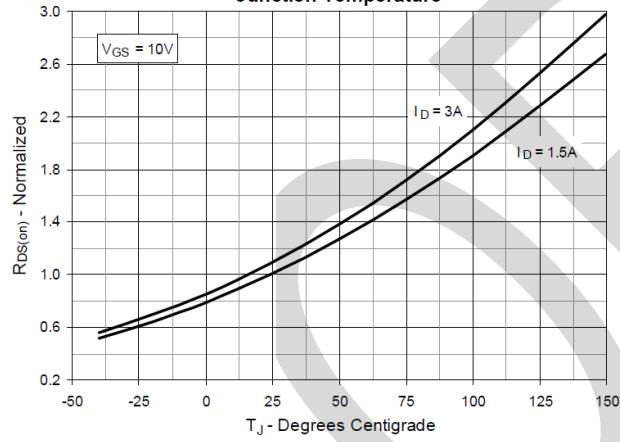
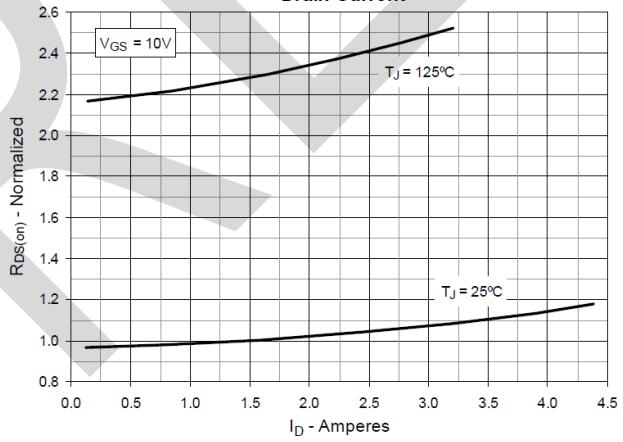
 Fig. 1. Output Characteristics @ $T_J = 25^\circ\text{C}$

 Fig. 2. Output Characteristics @ $T_J = 125^\circ\text{C}$

 Fig. 3. $R_{DS(on)}$ Normalized to $I_D = 1.5\text{A}$ Value vs. Junction Temperature

 Fig. 4. $R_{DS(on)}$ Normalized to $I_D = 1.5\text{A}$ Value vs. Drain Current


Fig. 5. Maximum Drain Current vs. Case Temperature

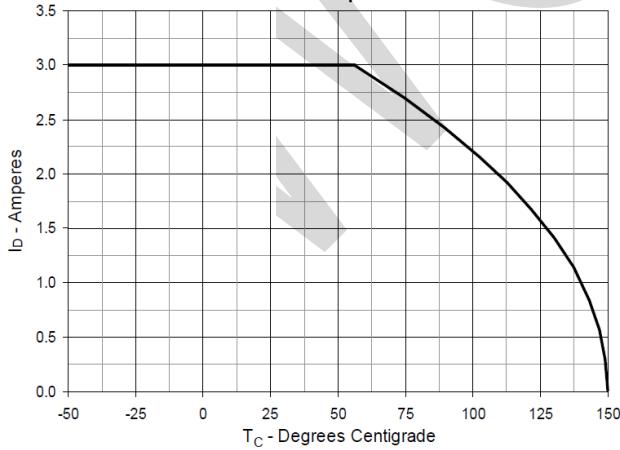
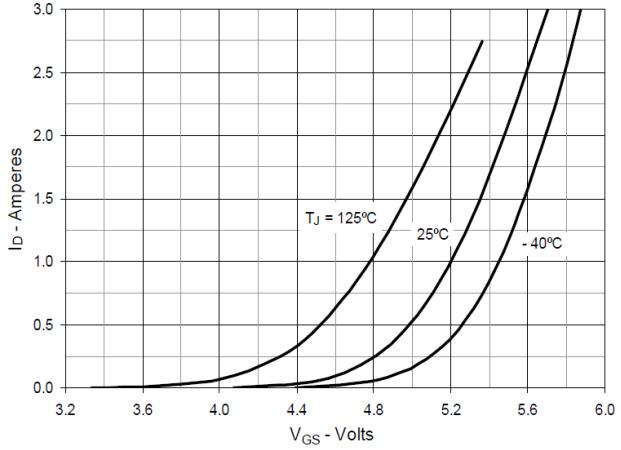


Fig. 6. Input Admittance



Typical Characteristics

Fig. 7. Transconductance

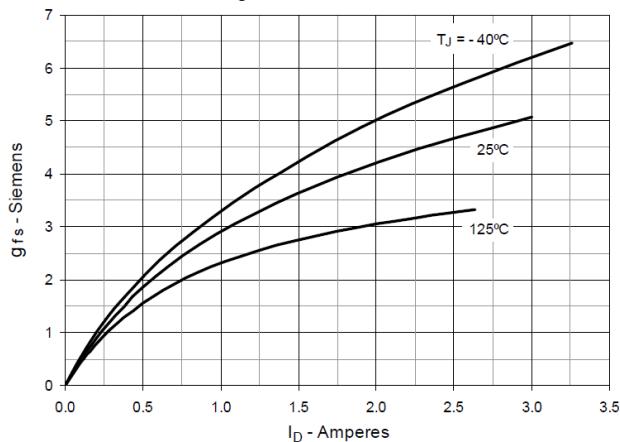


Fig. 8. Forward Voltage Drop of Intrinsic Diode

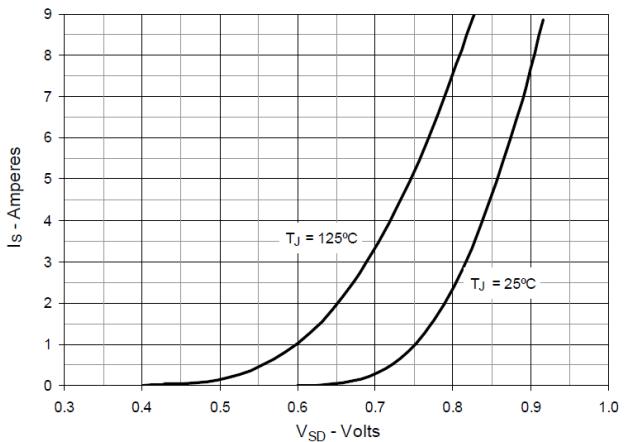


Fig. 9. Gate Charge

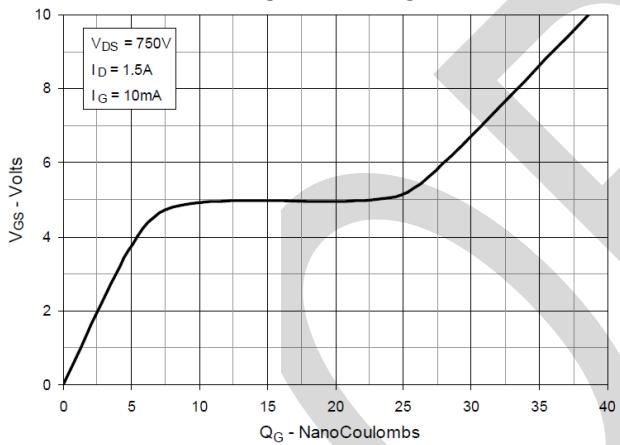


Fig. 10. Capacitance

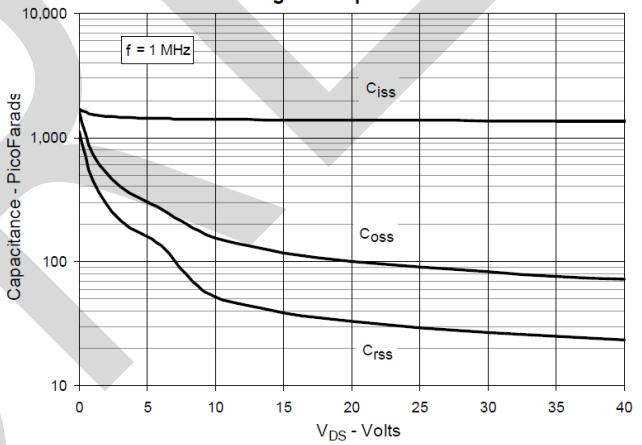


Fig. 11. Maximum Transient Thermal Impedance

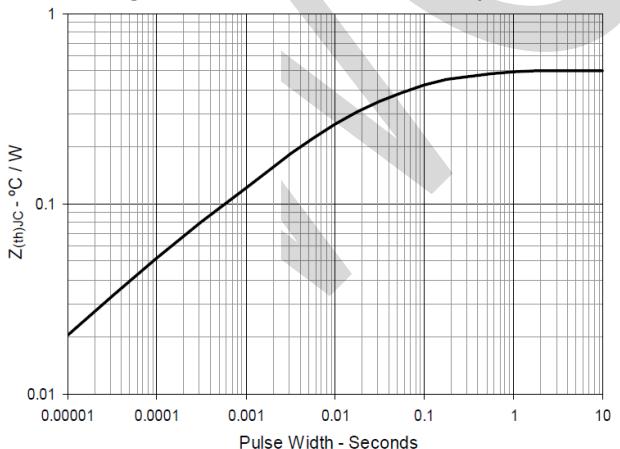
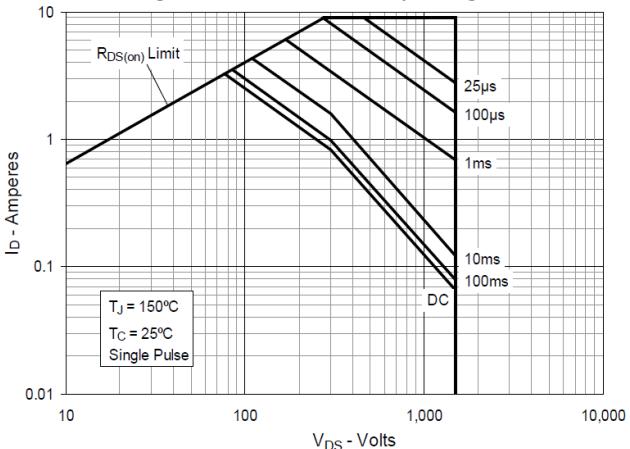
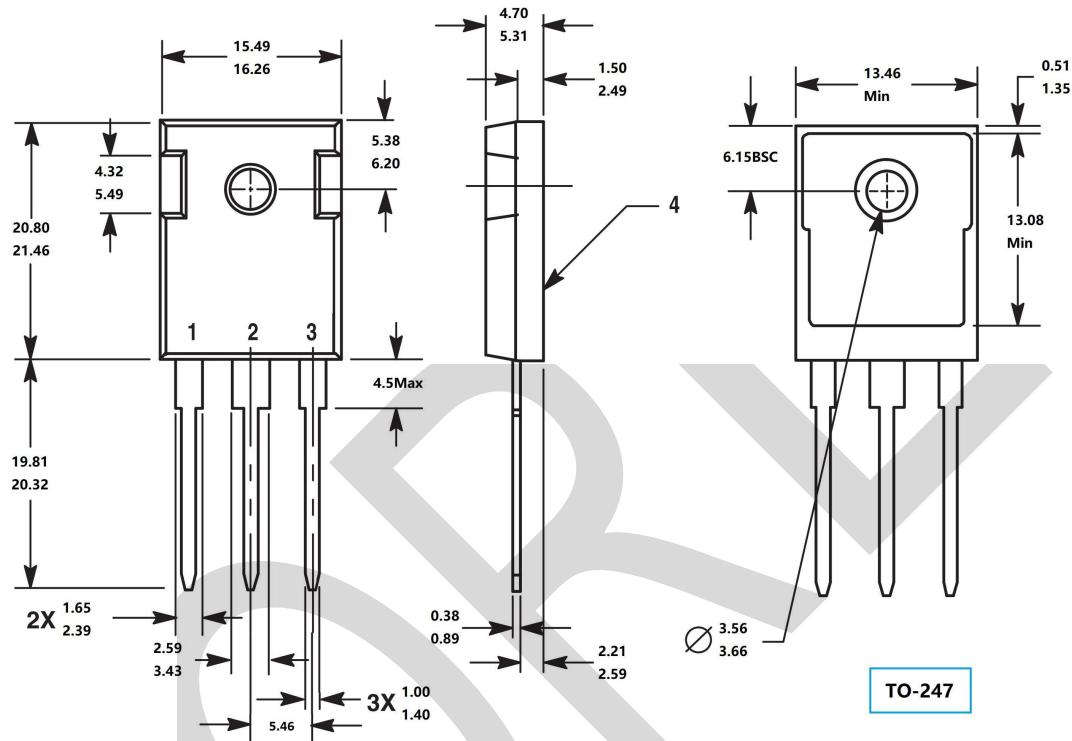


Fig. 12. Forward-Bias Safe Operating Area



PACKAGE OUTLINE DIMENSIONS

TO-247



TO-247